





60V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = 25°C
-60V	125m Ω @ V _{GS} = -10V	-3.4A
	190mΩ @ $V_{GS} = -4.5V$	-2.8A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor control
- Backlighting
- DC-DC Converters
- Power management functions

Features and Benefits

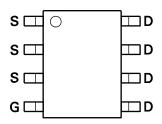
- Fast switching speed
- Low input capacitance
- "Green" component and RoHS compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

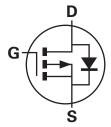
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish Matte Tin annealed over Copper lead frame.
 Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (approximate)







Top View



Equivalent Circuit

Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel	
ZXMP6A17N8TC	See below	13	12	2,500	

Notes: 1. Diodes, Inc. defines "Green" products as those which are RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website.

Marking Information



ZXMP = Product Type Marking Code, Line 1 6A17 = Product Type Marking Code, Line 2 YYWW = Date Code Marking YY = Year (ex: 09 = 2009) WW = Week (01 - 53)





Maximum Ratings @TA = 25°C unless otherwise specified

	Characteristic		Symbol	Value	Unit
Drain-Source voltage			V _{DSS}	-60	V
Gate-Source voltage			V _{GS}	±20	V
		(Note 3)		-3.42	
Continuous Drain current	$V_{GS} = 10V$	$T_A = 70$ °C (Note 3)	I_{D}	-2.73	Α
		(Note 2)		-2.7	
Pulsed Drain current V _{GS} = 10V (Note 4)		(Note 4)	I _{DM}	-15.6	Α
Continuous Source current (Body diode) (Note 3)		(Note 3)	Is	-3.4	Α
Pulsed Source current (Body diode) (Note 4)		(Note 4)	I _{SM}	-15.6	Α

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Power dissipation	(Note 2)	D.	1.56 12.5	W
Linear derating factor	(Note 3)	P _D	2.5 20	mW/°C
Thermal Resistance, Junction to Ambient	(Note 2)	D.	80	
mermai Resistance, Junction to Ambient	(Note 3)	$R_{\theta JA}$	50	°C/W
Thermal Resistance, Junction to Lead	(Note 5)	$R_{ hetaJL}$	32	
Operating and storage temperature range		T _J , T _{STG}	-55 to 150	°C

Notes:

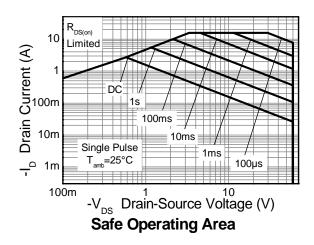
- 2. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- 3. Same as note (2), except the device is measured at $t \le 10$ sec.
- 4. Same as note (2), except the device is pulsed with D= 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.

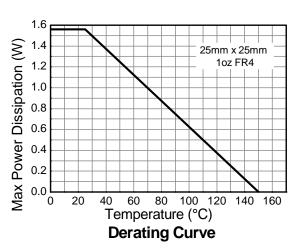
 5. Thermal resistance from junction to solder-point (at the end of the drain lead).

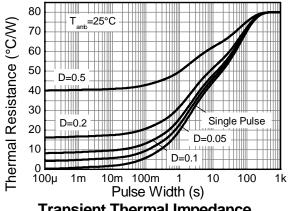


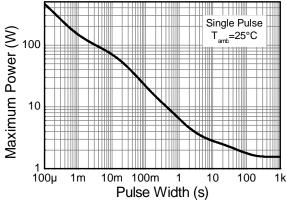


Thermal Characteristics









Transient Thermal Impedance

Pulse Power Dissipation





Electrical Characteristics @TA = 25°C unless otherwise specified

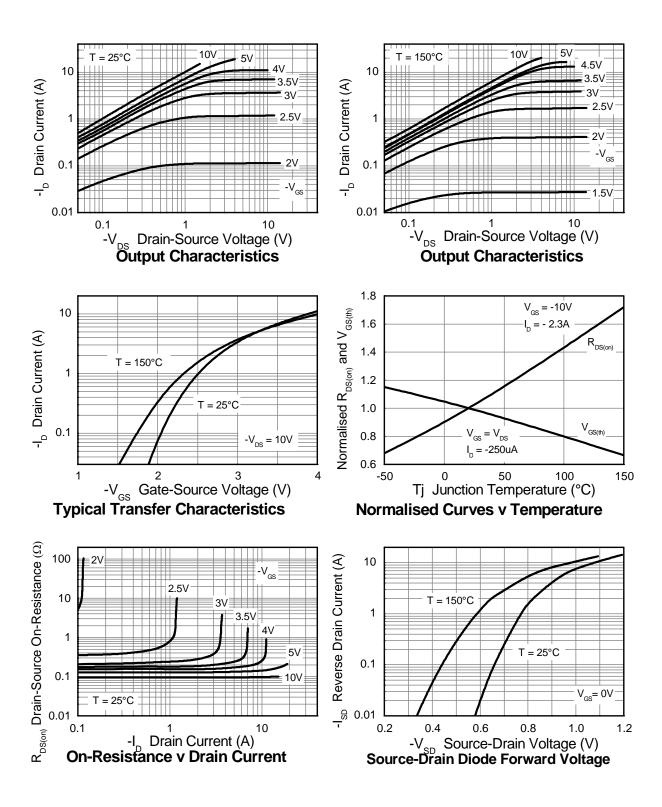
Characteristic	Symbol	Min	Тур	Max	Unit	Test Cond	lition
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	-60		_	V	$I_D = -250 \mu A, V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-0.5	μΑ	$V_{DS} = -60V, V_{GS} = 0$	V
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0$	OV
ON CHARACTERISTICS							
Gate Threshold Voltage	$V_{GS(th)}$	-1.0		_	V	$I_D = -250 \mu A, V_{DS} = V_{DS}$	V _{GS}
Static Drain-Source On-Resistance (Note 6)				0.125	Ω	$V_{GS} = -10V, I_{D} = -2.3$	3A
Static Drain-Source On-Resistance (Note 0)	R _{DS} (ON)	_		0.190	12	$V_{GS} = -4.5V, I_{D} = -1.$.9A
Forward Transconductance (Notes 6 & 7)	g _{fs}	_	4.7	_	S	$V_{DS} = -15V, I_{D} = -2.3$	3A
Diode Forward Voltage (Note 6)	V_{SD}	_	-0.85	-0.95	V	$I_S = -2.0A$, $V_{GS} = 0V$	'
Reverse recovery time (Note 7)	t _{rr}		25.1	_	ns	I _S = -1.7A, di/dt = 100A/μs	
Reverse recovery charge (Note 7)	Qrr	_	27.2	_	nC		
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C _{iss}	_	637	_	pF	.,	
Output Capacitance	Coss	_	70	_	pF	V _{DS} = -30V, V _{GS} = 0\ -f = 1MHz	V
Reverse Transfer Capacitance	C _{rss}	_	53	_	pF	1 = 1101112	
Total Gate Charge (Note 8)	Q_g	_	9.0	_	nC	$V_{GS} = -4.5V$	
Total Gate Charge (Note 8)	Qg	_	17.7	_	nC	VD	os = -30V
Gate-Source Charge (Note 8)	Qgs	_	1.6	_	nC	$V_{GS} = -10V$ I_D	= -2.2A
Gate-Drain Charge (Note 8)	Q_{gd}	_	4.4	_	nC	1	
Turn-On Delay Time (Note 8)	t _{D(on)}	_	2.6	_	ns		
Turn-On Rise Time (Note 8)	t _r	_	3.4	_	ns	V _{DD} = -30V, V _{GS} = -10V	
Turn-Off Delay Time (Note 8)	t _{D(off)}	_	26.2	_	ns	$I_D = -1A, R_G \cong 6.0\Omega$	
Turn-Off Fall Time (Note 8)	t _f	_	11.3	—	ns		

Notes:

- 6. Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
 7. For design aid only, not subject to production testing.
 8. Switching characteristics are independent of operating junction temperatures.

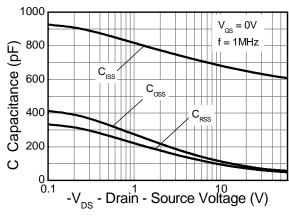


Typical Characteristics

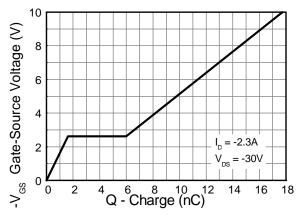




Typical Characteristics - continued

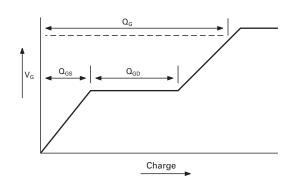


Capacitance v Drain-Source Voltage

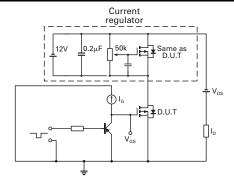


Gate-Source Voltage v Gate Charge

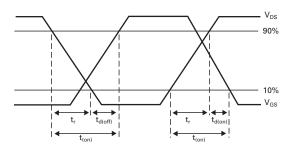
Test Circuits



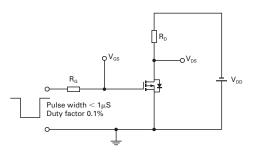
Basic gate charge waveform



Gate charge test circuit



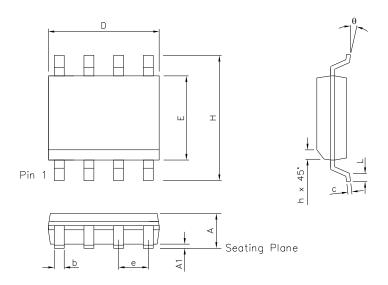
Switching time waveforms



Switching time test circuit

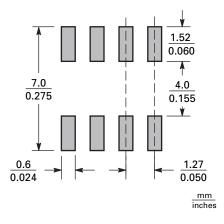


Package Outline Dimensions



DIM	Inc	Inches		Millimeters		Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
Α	0.053	0.069	1.35	1.75	е	0.050 BSC		1.27 BSC	
A1	0.004	0.010	0.10	0.25	b	0.013	0.020	0.33	0.51
D	0.189	0.197	4.80	5.00	С	0.008	0.010	0.19	0.25
Н	0.228	0.244	5.80	6.20	θ	0°	8°	0°	8°
Е	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27	-	-	-	-	-

Suggested Pad Layout







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